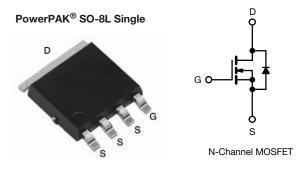
Vishay Siliconix

E Series Power MOSFET

PRODUCT SUMMARY				
V_{DS} (V) at T_J max. 700				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.520		
Q _g max. (nC)	44			
Q _{gs} (nC)	6			
Q _{gd} (nC)	9			
Configuration	Sing	le		



FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



APPLICATIONS

- Switch mode power supplies (SMPS)
- Flyback converter
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Consumer
 - Wall adaptors

ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and Halogen-free	SiHJ7N65E-T1-GE3

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	650	V
Gate-Source Voltage			V_{GS}	± 30	V
Continuous Drain Current (T _J = 150 °C)	V at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		7.9	
	V _{GS} at 10 V	T _C = 100 °C	I _D	5.0	Α
Pulsed Drain Current a			I _{DM}	17	
Linear Derating Factor				0.77	W/°C
Single Pulse Avalanche Energy b			E _{AS}	68	mJ
Maximum Power Dissipation			P _D	96	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope T _J = 125 °C			d\//d+	70	1//20
Reverse Diode dV/dt ^d			dV/dt	14	V/ns

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 2.2 A.
- c. $I_{SD} \le I_D$, dI/dt = 100 A/ μ s, starting $T_J = 25$ °C.

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	52	65	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	1.0	1.3	G/ VV



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.8	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Cata Saurea Laglana	1	,	$V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
Gate-Source Leakage	I _{GSS}	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μA
Zero Gate Voltage Drain Current		V _{DS} =	V _{DS} = 650 V, V _{GS} = 0 V		-	1	μA
Zero Gate Voltage Drain Gurrent	I _{DSS}	$V_{DS} = 520 \text{ V}$, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μΑ
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 3.5 A	-	0.520	0.598	Ω
Forward Transconductance	9fs	V _{DS} =	= 30 V, I _D = 3.5 A	-	2.3	-	S
Dynamic							
Input Capacitance	C _{iss}	$V_{GS} = 0 V$,		-	820	-	
Output Capacitance	C _{oss}	,	$V_{\rm DS} = 100 \text{ V},$	-	48	-	
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz	-	4	-	_
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	٧, ٥٠	/+a 500 // // 0 //	-	33	-	pF
Effective Output Capacitance, Time Related ^b	C _{o(tr)}	V _{DS} = 0 \	/ to 520 V, V _{GS} = 0 V	-	118	-	
Total Gate Charge	Q_g			-	22	44	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 3.5 \text{ A}, V_{DS} = 520 \text{ V}$	-	6	-	nC
Gate-Drain Charge	Q _{gd}			-	9	-	
Turn-On Delay Time	t _{d(on)}			-	16	32	
Rise Time	t _r	$V_{DD} =$	520 V, I _D = 3.5 A,	-	18	36	
Turn-Off Delay Time	t _{d(off)}	V _{GS} =	$=$ 10 V, R _g = 9.1 Ω	-	30	60	ns
Fall Time	t _f			-	18	36	
Gate Input Resistance	R _g		f = 1 MHz	0.4	0.8	1.6	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	MOSFET symbol showing the		-	7.9	
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	17	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C	S, I _S = 3.5 A, V _{GS} = 0 V	-	0.9	1.2	V
Reverse Recovery Time	t _{rr}	-		-	299	598	ns
Reverse Recovery Charge	Q _{rr}	$T_J = 25$	5 °C, I _F = I _S = 3.5 A, 100 A/μs ^{, V} _B = 25 V	-	2.9	5.8	μC
Reverse Recovery Current	I _{RRM}	ui/at =	100 A/µS, 'R = 20 V	-	16	-	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

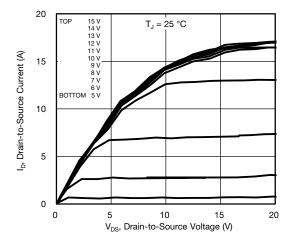


Fig. 1 - Typical Output Characteristics

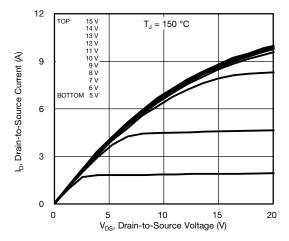


Fig. 2 - Typical Output Characteristics

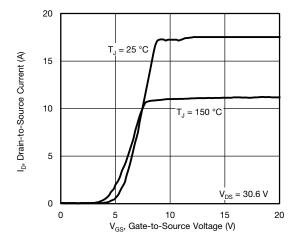


Fig. 3 - Typical Transfer Characteristics

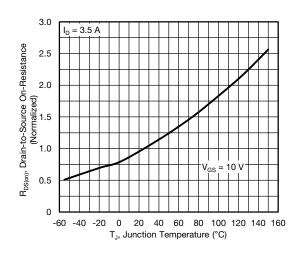


Fig. 4 - Normalized On-Resistance vs. Temperature

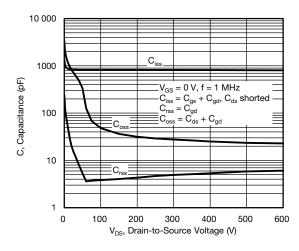


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

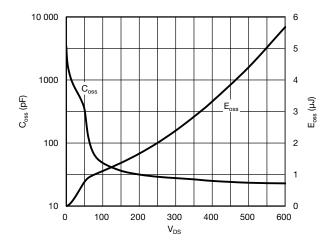


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



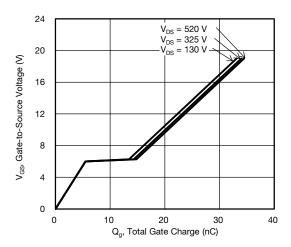


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

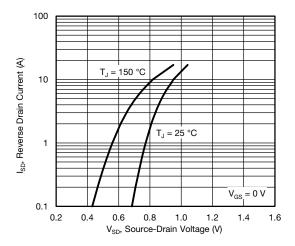


Fig. 8 - Typical Source-Drain Diode Forward Voltage

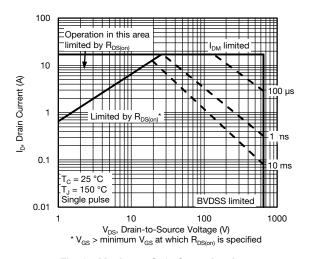


Fig. 9 - Maximum Safe Operating Area

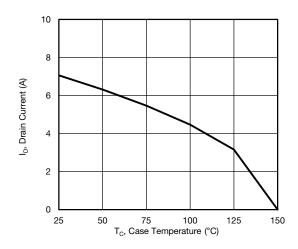


Fig. 10 - Maximum Drain Current vs. Case Temperature

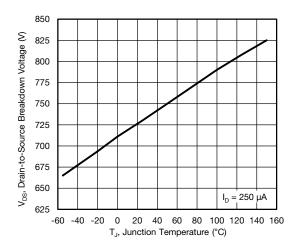


Fig. 11 - Temperature vs. Drain-to-Source Voltage



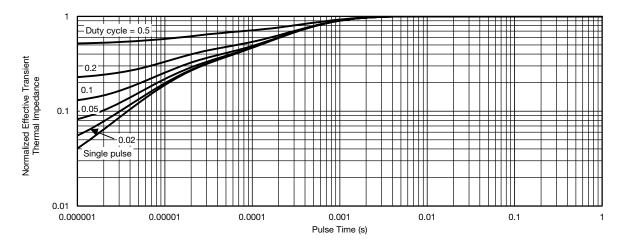


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

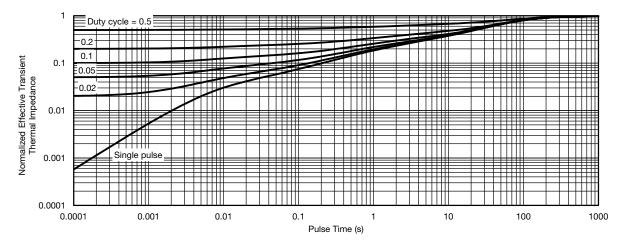


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

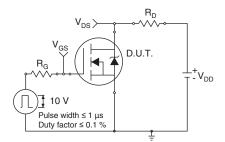


Fig. 14 - Switching Time Test Circuit

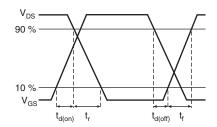


Fig. 15 - Switching Time Waveforms



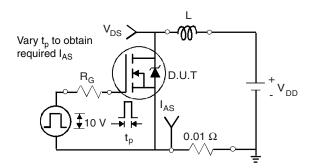


Fig. 16 - Unclamped Inductive Test Circuit

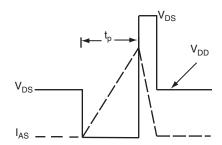


Fig. 17 - Unclamped Inductive Waveforms

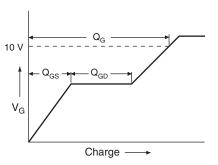


Fig. 18 - Basic Gate Charge Waveform

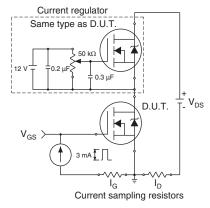
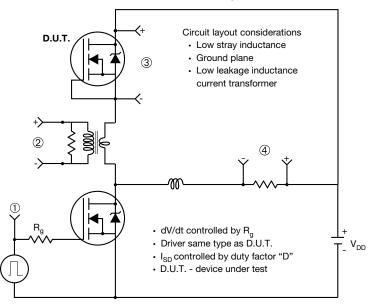


Fig. 19 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



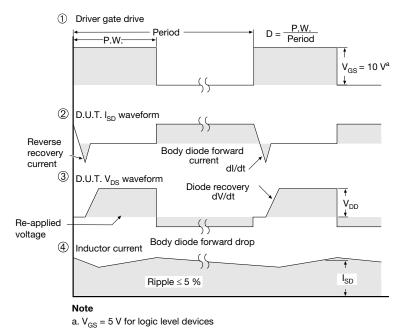
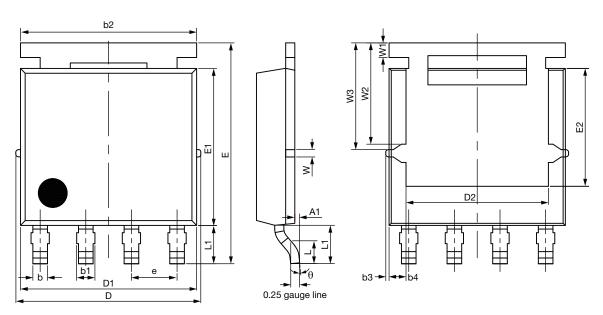


Fig. 20 - For N-Channel

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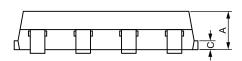
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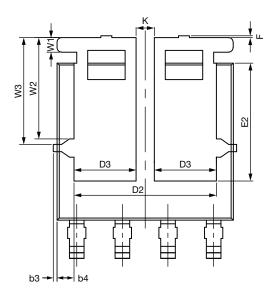
PowerPAK® SO-8L Case Outline for Non-Al Parts



Topside view

Backside view (single)





Backside view (dual)





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DIM	MILLIMETERS			INCHES		
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
Α	1.00	1.07	1.14	0.039	0.042	0.045
A1	0.00	-	0.127	0.00	-	0.005
b	0.33	0.41	0.48	0.013	0.016	0.019
b1	0.44	0.51	0.58	0.017	0.020	0.023
b2	4.80	4.90	5.00	0.189	0.193	0.197
b3		0.094			0.004	
b4		0.47			0.019	
С	0.20	0.25	0.30	0.008	0.010	0.012
D	5.00	5.13	5.25	0.197	0.202	0.207
D1	4.80	4.90	5.00	0.189	0.193	0.197
D2	3.86	3.96	4.06	0.152	0.156	0.160
D3	1.63	1.73	1.83	0.064	0.068	0.072
е		1.27 BSC		0.050 BSC		
E	6.05	6.15	6.25	0.238	0.242	0.246
E1	4.27	4.37	4.47	0.168	0.172	0.176
E2	3.18	3.28	3.38	0.125	0.129	0.133
F	-	-	0.15	-	-	0.006
L	0.62	0.72	0.82	0.024	0.028	0.032
L1	0.92	1.07	1.22	0.036	0.042	0.048
K		0.51		0.020		
W	0.23		0.009			
W1	0.41		0.016			
W2	2.82		0.111			
W3	2.96		0.117			
θ	0°	-	10°	0°	-	10°

ECN: T16-0221-Rev. D, 16-May-16

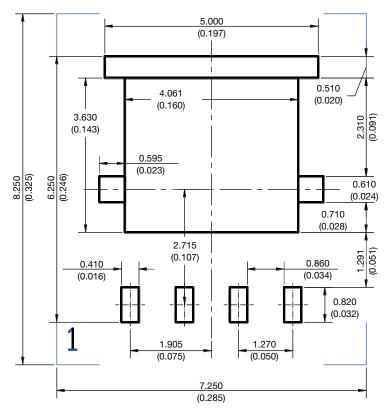
DWG: 5976

Note

Millimeters will gover



RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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Vishay

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Revision: 02-Oct-12 Document Number: 91000

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